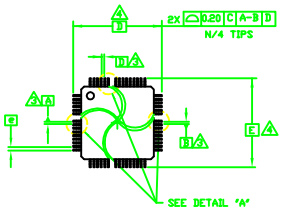
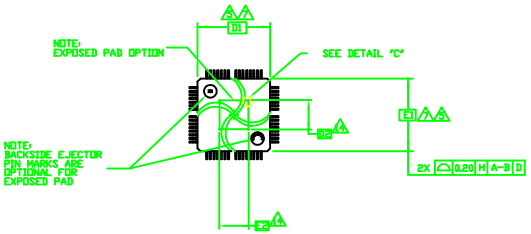
REVISION HISTORY				
REV	DESCRIPTION	DATE	ORIGINATED	RELEASED
00	INITIAL RELEASE PER DCN #P80488.	07/28 1998	LSE	XXX
01	INCORPORATED PER DCN #P90089. (ENG-PD-084/A BECOMES 40579/01)	02/04 1999	LSE	XXX
02	INCORPORATED PER DCN #D26830.	07/05 2007	AAYRE	AAYRE

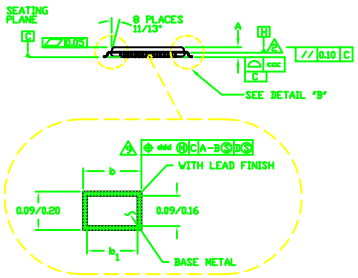
TOP VIEW

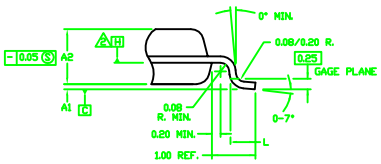


BOTTOM VIEW



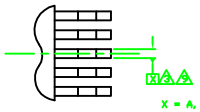
DETAIL "C"
(EXPOSED PAD CORNER DETAIL)



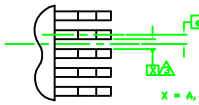


DETAIL "B"

ODD LEAD SIDES



EVEN LEAD SIDES



DETAIL "A"

XXXX	XXXX	XXXX	XXXX
DESCRIPTION	MATERIAL	PLATE	SID NUMBER

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL: X.X ±0.1 mm; X.XX ±0.05 mm; X.XXX ±0.025 mm

ANGULAR: ±1°

INTERPRET DIM AND TOL PER ASME Y14.5M – 1994

PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DRAWN: LHERA	05/31 1999
CHECKED: TICHAM/AALVA	05/31 1999
APPROVED: LCANO	05/31 1999
RELEASED: MHELA	05/04 1999

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor / ANAM Technology Semiconductor

TITLE: PACKAGE OUTLINE, MATRIX, ePAD TQFP, 5 X 5 mm BODY, 1.00/0.10 mm FORM, 1.00 mm THICK (OPTIONAL ePAD)

SIZE	DWG NUMBER	REV
A3	40579	02

SCALE	CUSTOMER CODE	SHEET
5:1	XXXX	1 OF 2

FORM NO. MDFORM3J.DWG